



# Efficient Flip-Flop Designs for SET/SEU Mitigation with Tolerance to Crosstalk Induced Signal Delays

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# Outline

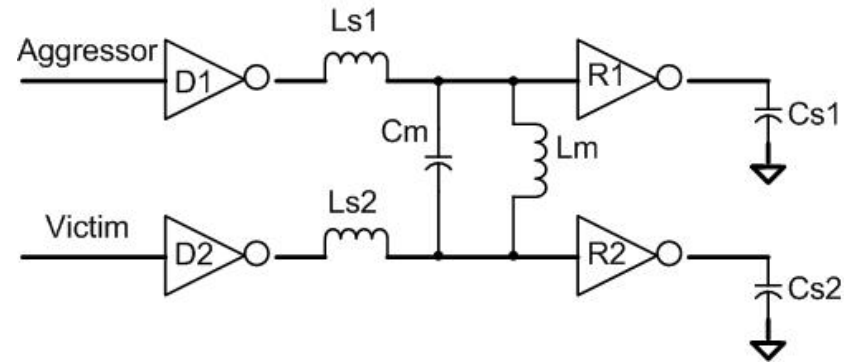
- Introduction to Soft Errors & Crosstalk
- Reliability issues
- Prior work
- Proposed designs (Design 1 & Design 2)
- Design validation
- Comparison with current designs
- Performance limitations & penalties
- Conclusion

# Soft Errors

- "Soft errors induced the highest failure rate of all other reliability mechanisms combined." – Robert Baumann (TI)
- Charged particles impinging on circuit node disrupt existing node voltage
- Generated transient voltage may cross noise margins on receiving gate resulting in erroneous operation
- Many factors influence this behavior
- Fabrication technology, nature of circuit surrounding the impact site, supply voltage and intensity of radiation are main factors. Resulting effect manifested in two forms
  - Single Event Upset (SEU), Single Event Transient (SET)
- Critical charge ( $Q_{crit}$ ) required to affect node voltage decreases significantly with decreasing feature sizes

# Interconnect Crosstalk

- Inductive + Capacitive coupling leads to crosstalk
- Increasing operational frequencies combined with decreasing interconnect lengths cause dominant inductive coupling
- Severity depends on signal transition times, interconnect spacing, operational frequency and driver sizing
- Decreasing supply voltages lead to lower noise margins resulting in more voltage disruptions at receiving end

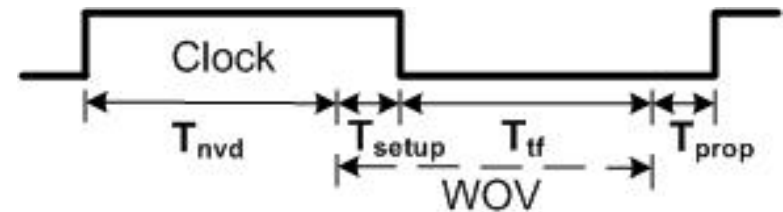


# SEU/SET Effects

- A particle hit may result in either an SEU/SET depending on the position of affected node.
  - Regenerative feedback results in an SEU
  - Propagation results in an SET
- $Q_{transferred} > Q_{crit}$  particle hit on an internal node of storage element results in a bit flip
- SET must arrive at input during latching window of a storage element to corrupt data
- Period for which a latch is susceptible to particle hits is called Window of Vulnerability (**WoV**)

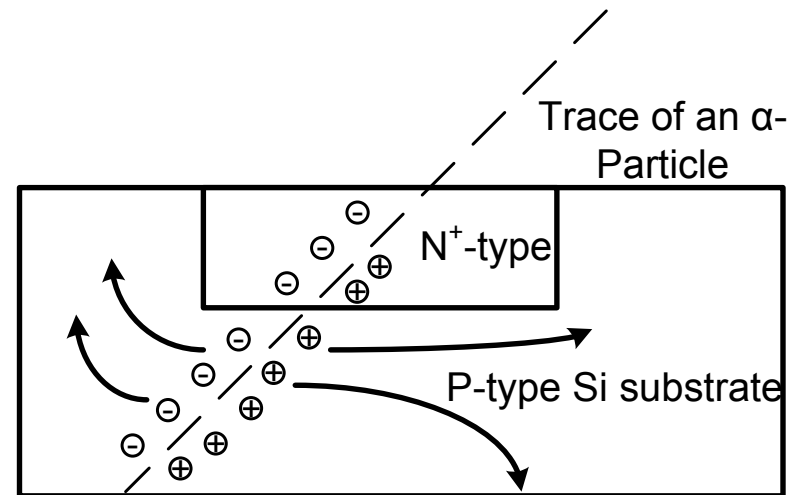
# Window of Vulnerability (WoV) for a Latch

- Transparent when Clock=1, Opaque when Clock=0
- $T_{nvd}$  - Period for which latch is transparent
- $T_{setup}$  - Setup time
- $T_{tf}$  - Period during which a hit on the internal node can flip the stored bit value
- $T_{prop}$  - Time required for the error to propagate to latch output



# Need for Immunity from SEU/SETs

- Soft Error Rate (SER) measured in Failure in Time (FIT), 1 FIT= 1 System-level error every  $10^9$  hours
- Sigma-6 compliant systems (network routers, storage systems) - downtime penalty in millions
- Shrinking feature sizes /lower supply voltages aggravate this problem.



# Prior Work

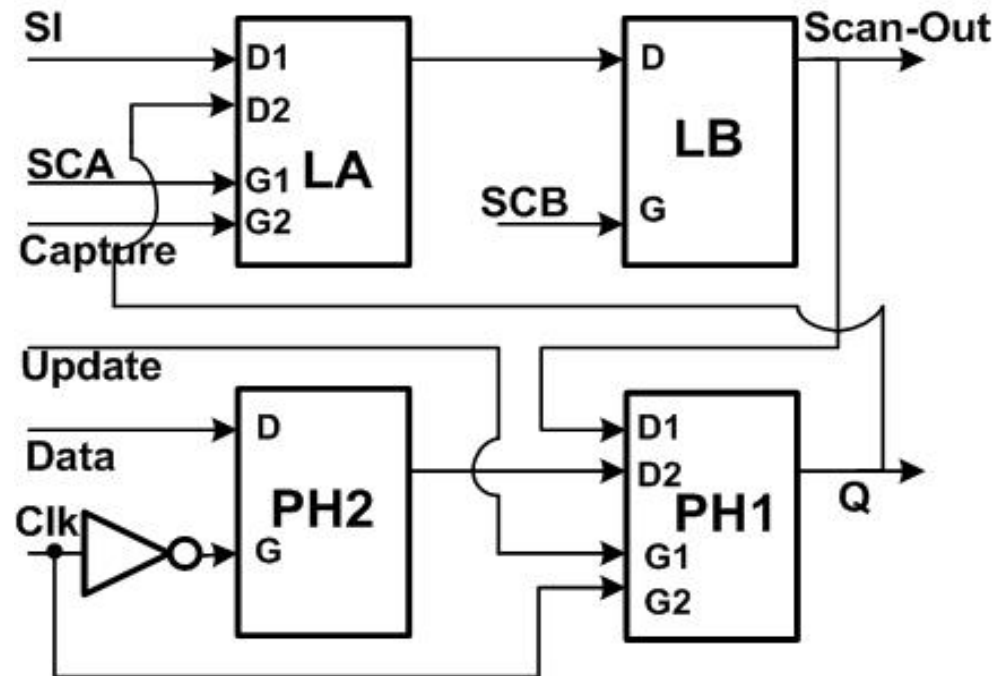
- Cha H. and Patel J.H., 'Latch design for transient pulse tolerance', ICCD, 1994
- Hass K.J. *et al.*, 'Mitigating single event upsets from combinational logic', NASA Symposium on VLSI Design, 1998
- D. Mavis and P. Eaton. 'Soft Error Rate Mitigation Techniques for Modern Microcircuits', IRPS, 2002
- Mitra *et al.*, 'Robust System Design with Built-In Soft Error Resilience', IEEE Computer, 2005
- Roy *et al.*, 'Low-overhead design of soft-error-tolerant scan flip-flops with enhanced-scan capability', ASPCDA, 2006
- Breuer *et al.*, "Test Generation in VLSI circuits for Crosstalk noise", ITC, 1998
- Dey *et al.*, "On-line Testing of Multi-source Noise-induced Errors on the Interconnects and Buses of System-on-Chips.", ITC, 2002

# Drawbacks of Existing Solutions

- Use of error correcting codes involves high hardware overhead and timing penalty
- *Triple Modular Redundancy* (TMR) involves high hardware & power overheads
- Designs developed mostly perform error blocking and only for a subset of the **WoV**. No error correction attempted.
- Concurrent error correction mechanisms need to satisfy the following
  - Account for the entire WoV
  - Avoid a single point of failure
- For testing Xtalk sites, algorithm efficiency greatly reduces with increasing circuit size
- Detection based on wire inductance, accurate extraction commercially unfeasible

# The Basic Scan Flip-Flop (BSFF)

- PH2/PH1-System  
Master/Slave, LA/LB-  
Scan Master/Slave
- Data, Clk used during  
functional mode of  
operation
- SI-Scan Input, SCA/SCB-  
Scan clocks, Capture-  
used to load system  
response, Update-loads  
test bit to PH1
- BSFF vulnerable to
  - Incoming Transients  
(SET)
  - Hit on internal nodes  
(SEU)

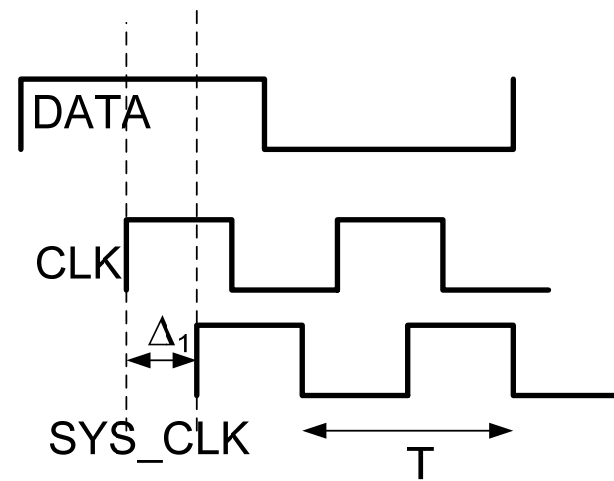
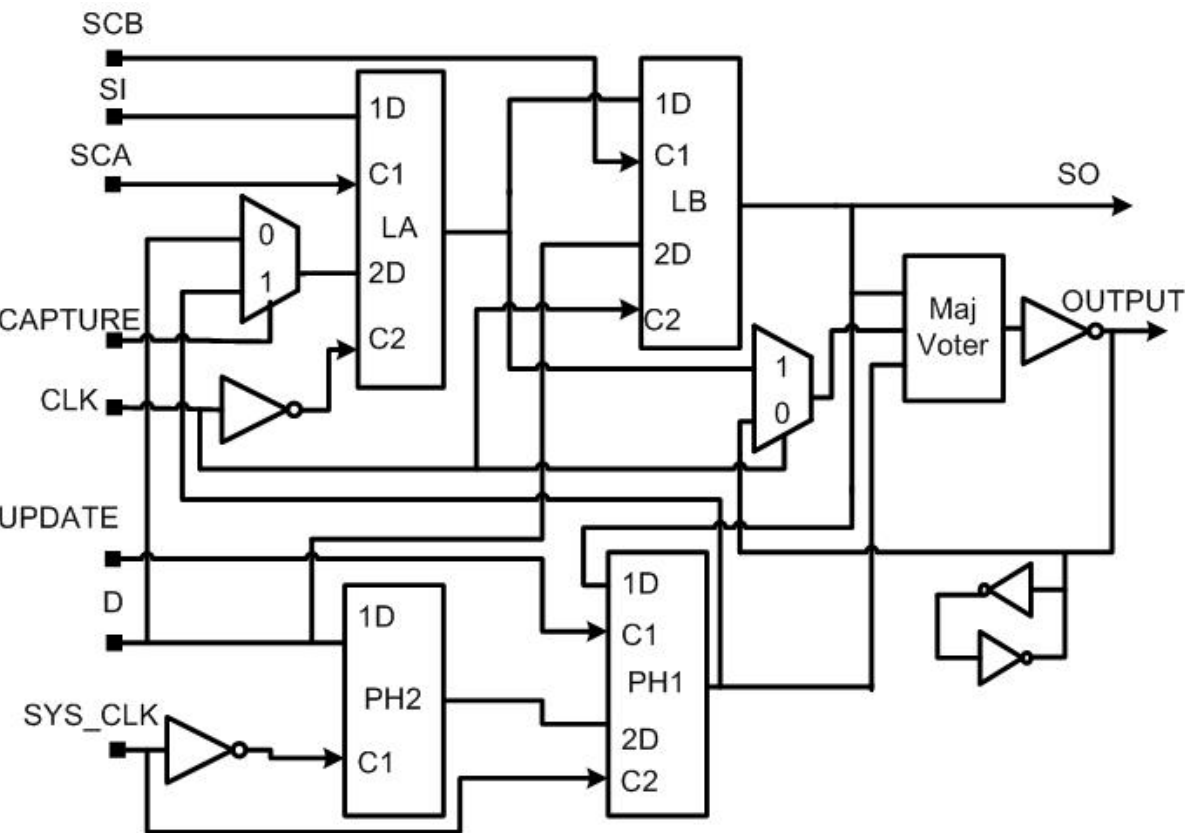


# Our Work

# Ideas Behind our Proposed Design

- 1 SET/SEU assumed per clock cycle
- Latches LA & LB idle during functional mode store redundant data
- Concurrent error detection/correction targeted
- Must provide flexible tradeoff between operational frequency & soft-error tolerance with minimum hardware overhead
- Modified design must be fully testable

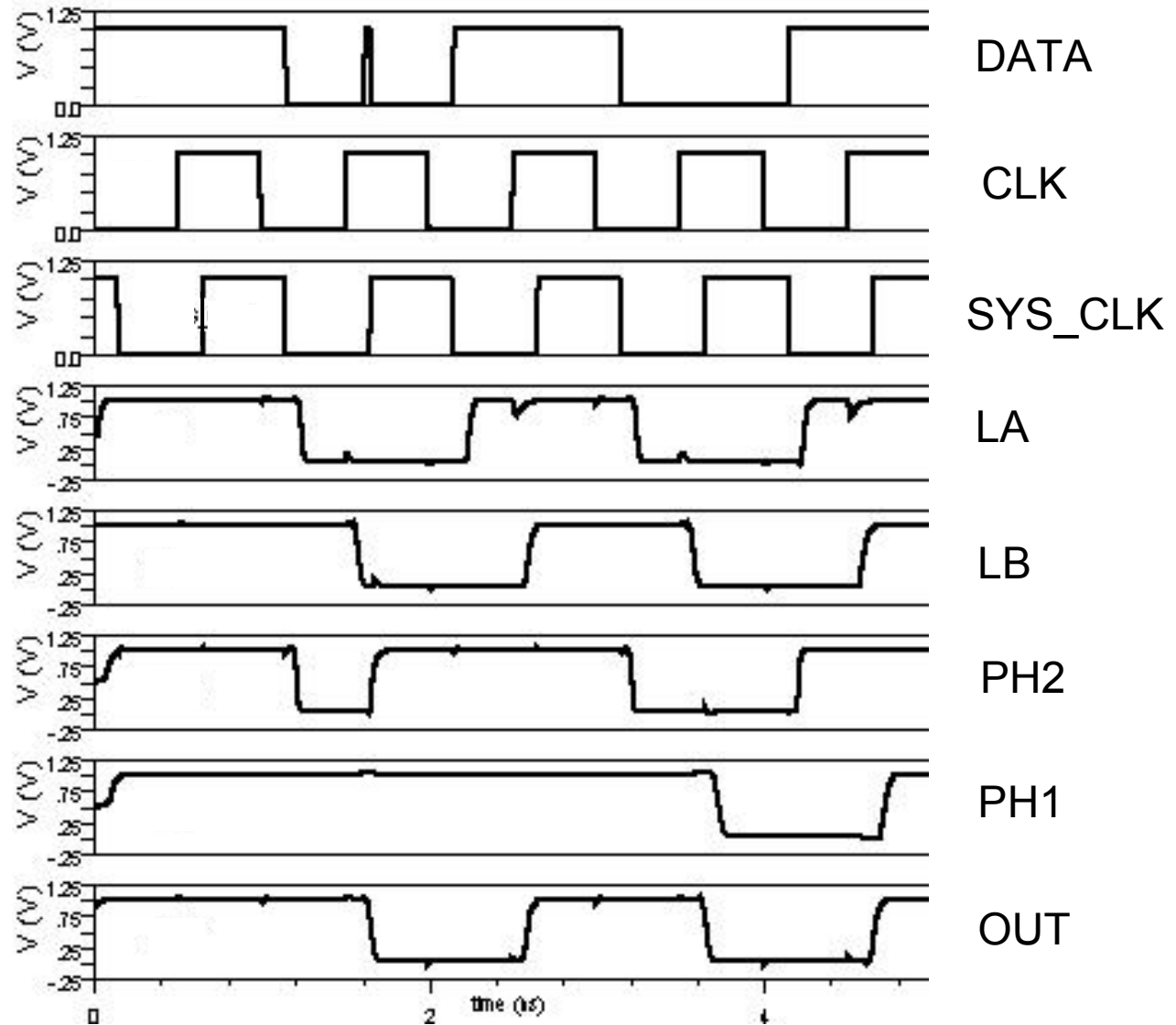
# Crosstalk & SEU Tolerant Flip-Flop (XSEUFF1)



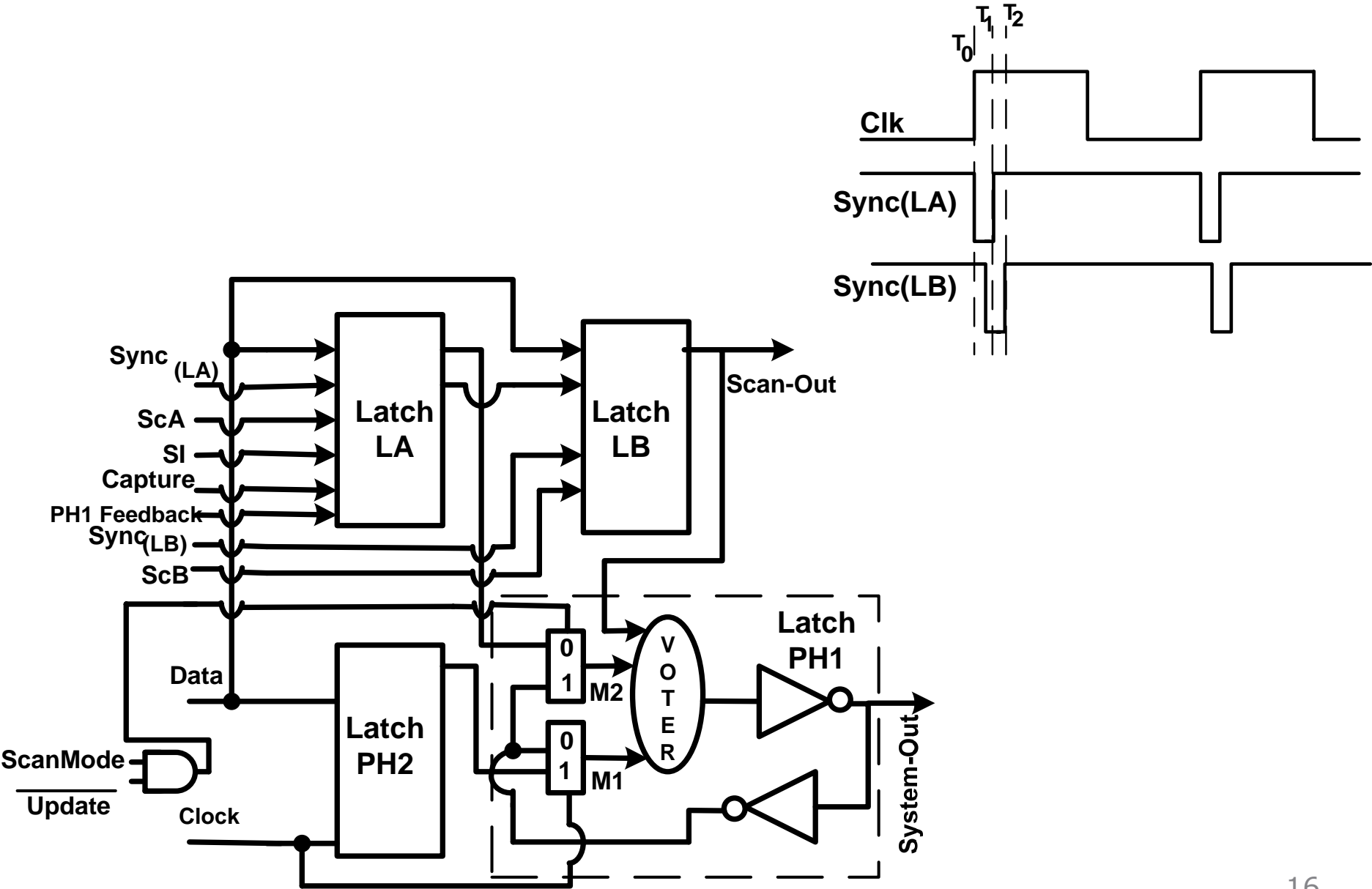
# Working of XSEUFF1

- A synchronous signal 'Clk' (advanced w.r.t 'Sys\_Clk')-gating signal for scan master/slave (LA/LB)
- Data loaded first into 'LA' then 'PH2' and finally 'LB'
- Majority Voter (MV) loads result to keeper on output node while Clk=1-Result: Immunity from SET
- When Clk=0, keeper/LB/PH1 feed MV, protected from SEU
- SET tolerance parameter ( $\Delta_1$ ) is based upon the desired ***Width of Maximum Tolerable Transient*** pulse (***WMTT***)
- $\Delta_1 = t_{setup} + WMTT + t_{hold}$

# Response of the XSEUFF1



# The XSEUFF2



# Working of the XSEUFF2

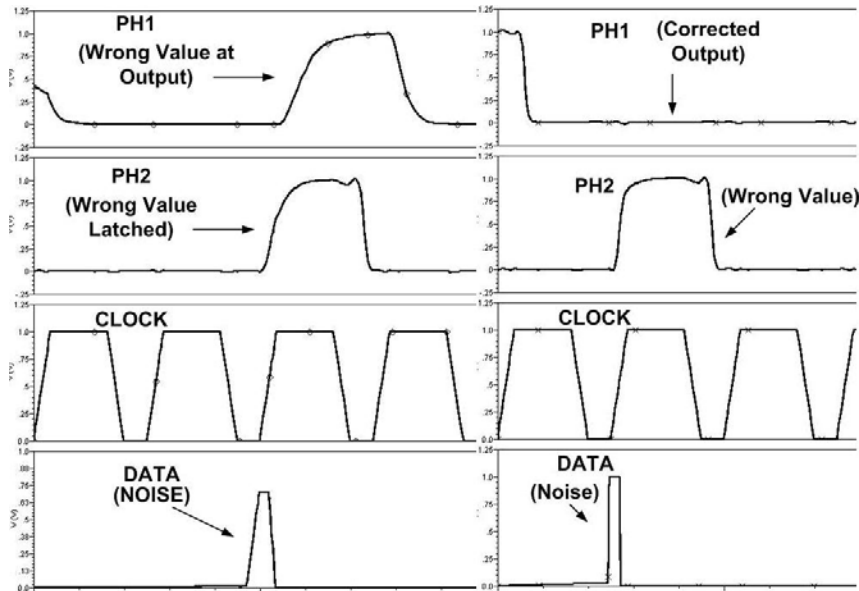
- Two synchronous signals, ' $\text{Sync}_{(LA)}$ ' & ' $\text{Sync}_{(LB)}$ ' control latches LA & LB respectively
- Latch PH1 modified to incorporate MV. LA and LB continuously vote on bit stored in modified PH1 when  $\text{Sync}_{(LA)}=1$  &  $\text{Sync}_{(LB)}=1$  (immunity from SEU)
- LA, PH1, LB vote when respective control signals are low (immunity from SETs)
- Lower transistor overhead, but need a signal generator
- Is capable of handling an SET + SEU within the same clock cycle under certain conditions



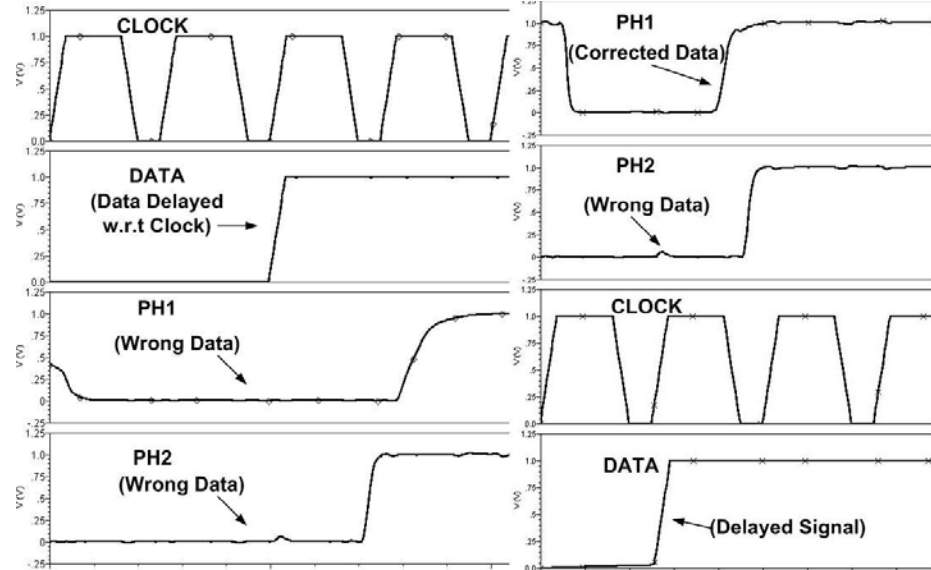
# Tolerance Limits of the XSEUFF2

- $WMTT = \{T_2 - t_{setup} + \max(t_{cd(LB),r}, t_{cd(LB),f})\} - \{T_0 + t_{hold} - \min(t_{cd(PH2),r}, t_{cd(PH2),f})\}$
- Capable of tolerating signal delays due to crosstalk effects
- Maximum tolerable delay ( $\Delta_{Max}$ ) depends on width of pulses on  $Sync_{(LA)}$  and  $Sync_{(LB)}$
- $\Delta_{Max} = \{T_1 - t_{setup} + \max(t_{cd(LA),r}, t_{cd(LA),f})\} - \{T_0 - t_{setup}\}$
- $t_{cd(LB),r}, t_{cd(LB),f}$  – rise/fall times of muxes feeding data inputs of latch LB
- $T_0, T_1$  &  $T_2$  arrival instants of active edges of signals Clk,  $Sync_{(LA)}$  &  $Sync_{(LB)}$  respectively

# Response of the XSEUFF2



BSFF Vs XSEUFF2  
(Noise Pulses)



BSFF Vs XSEUFF2  
(Signal Delays)

# Comparisons between various schemes

Type of Flip-Flop	Transistor Overhead	Timing Penalty	Power Overhead	Error Correction
BSFF (Mitra <i>et al.</i> )	1	1	1	NO
EBSFF (Mitra <i>et al.</i> )	1.13	1.23	2.77	NO
ETSFF (Mitra <i>et al.</i> )	1.15	1.01	2.13	NO
EBSHFF (Roy <i>et al.</i> )	0.91	1.25	1.72	YES
XSEUFF1	1.54	1	2.7	YES
XSEUFF2	1.37	1.25	1.95	YES

# Overheads for ISCAS '89 Benchmarks

<b>Circuit</b>	<b>XSEUFF1 (%)</b>	<b>XSEUFF2 (%)</b>
S5378	29.3	20.2
s9234	21.8	15
s13207	32.1	22.1
s15850	27.3	18.9
s35932	31.3	21.6
s38417	29.9	20.6
s38584	27	18.6
<b>Average</b>	<b>28.4</b>	<b>19.6</b>

# Limitations & Conclusion

- XSEUFF1 & XSEUFF2 offer flexible tradeoffs between reliability and performance
- XSEUFF1 has lower timing penalty, but higher hardware/power overheads, XSEUFF2 has relatively lower hardware/power overheads, but higher timing penalty
- Need for designs tolerant to SEU/SET increasing with shrinking technology
- Better packaging offers higher SEU/SET immunity, cost increases significantly. Hence, solution must lie within the design.
- SEU immune instances can be used in conjunction with a system-level tolerant scheme to optimize performance + tolerance

**Thank You!**